IGBT

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Field Stop (FS) Trench construction, and provides superior performance in demanding switching applications, offering both low on-state voltage and minimal switching loss. The IGBT is well suited for resonant or soft switching applications. Incorporated into the device is a rugged co-packaged free wheeling diode with a low forward voltage.

Features

- Low Saturation Voltage using Trench with Fieldstop Technology
- Low Switching Loss Reduces System Power Dissipation
- Optimized for Low Case Temperature in IH Cooker Application
- Low Gate Charge
- These are Pb–Free Devices

Typical Applications

- Inductive Heating
- Consumer Appliances
- Soft Switching

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-emitter voltage	V _{CES}	1200	V
Collector current @ Tc = 25°C @ Tc = 100°C	I _C	40 20	A
Pulsed collector current, T _{pulse} limited by T _{Jmax}	I _{CM}	м 200	
Diode forward current @ Tc = 25°C @ Tc = 100°C	I _F	40 20	A
Diode pulsed current, T _{pulse} limited by T _{Jmax}			A
Gate-emitter voltage	V_{GE}	±20	V
Power Dissipation @ Tc = 25°C @ Tc = 100°C	P _D	192 77	W
Operating junction temperature range	TJ	-55 to +150	°C
Storage temperature range	T _{stg}	–55 to +150	°C
Lead temperature for soldering, 1/8" from case for 5 seconds	T _{SLD}	260	°C

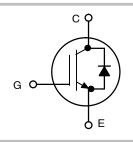
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

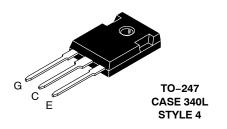


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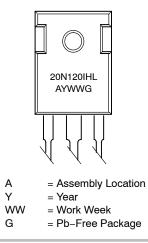
http://onsemi.com

20 A, 1200 V V_{CEsat} = 1.80 V E_{off} = 0.7 mJ





MARKING DIAGRAM



ORDERING INFORMATION

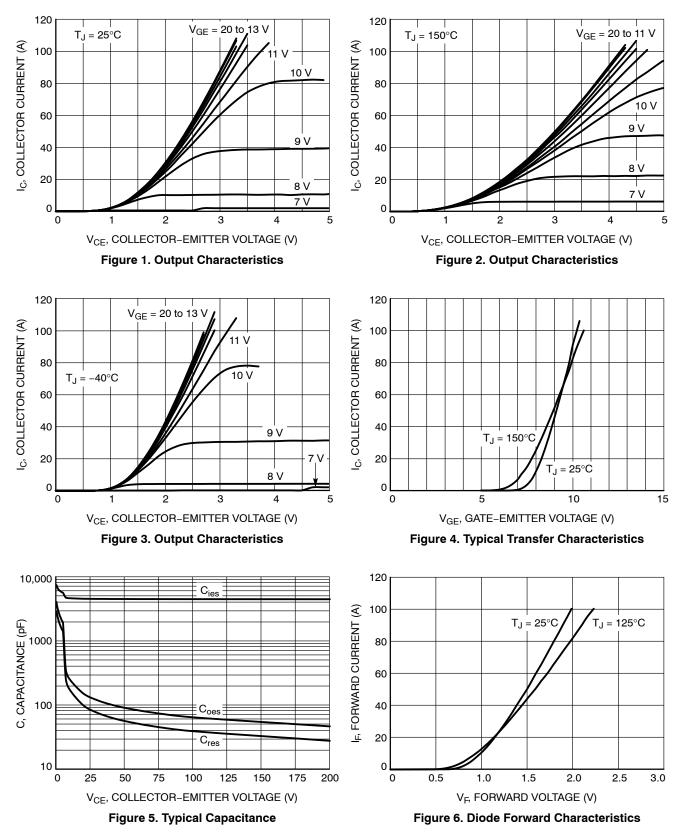
Device	Package	Shipping
NGTB20N120IHLWG	TO-247 (Pb-Free)	30 Units / Rail

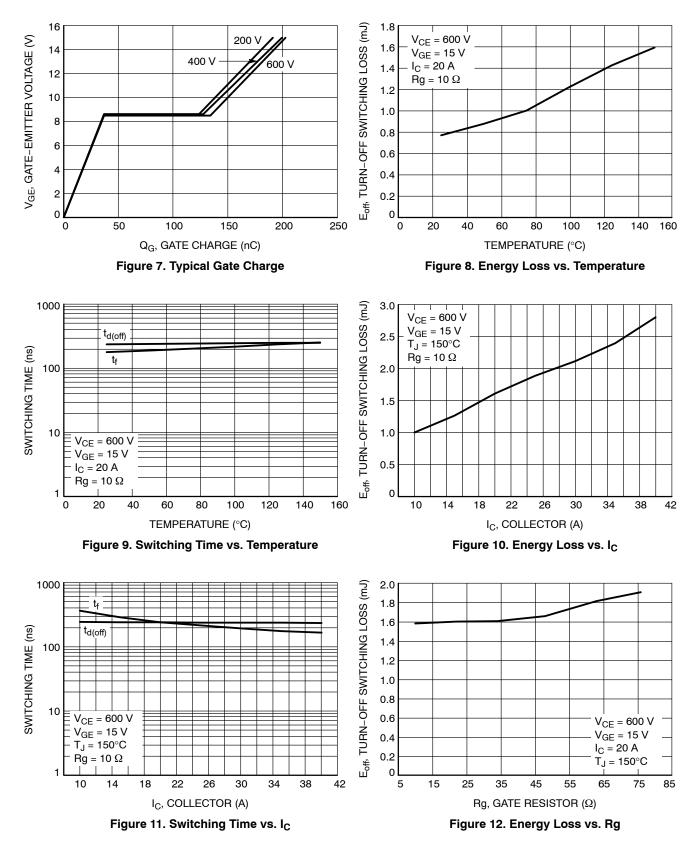
THERMAL CHARACTERISTICS

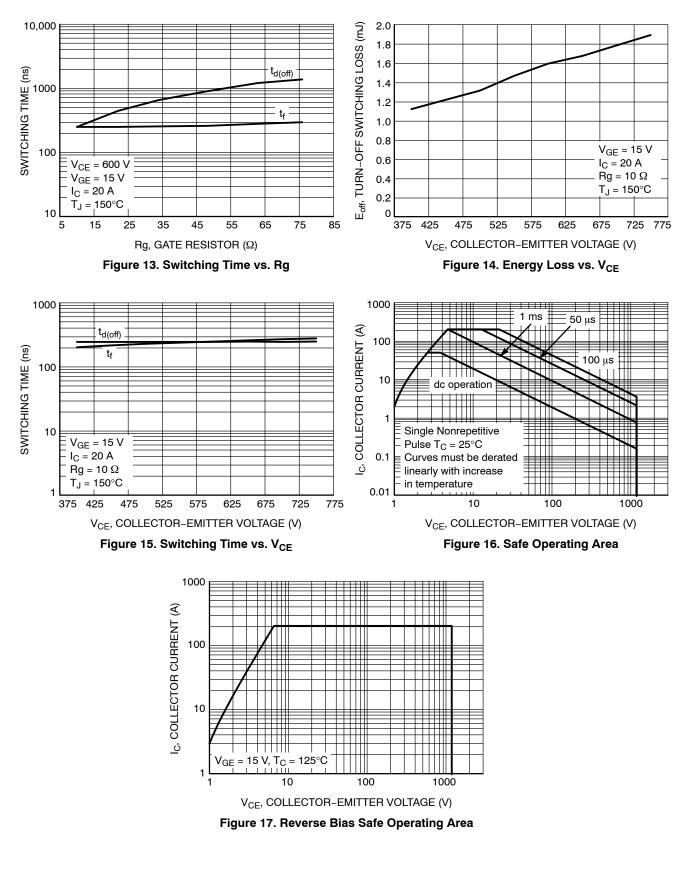
Rating	Symbol	Value	Unit
Thermal resistance junction-to-case, for IGBT	$R_{ hetaJC}$	0.65	°C/W
Thermal resistance junction-to-case, for Diode	$R_{ hetaJC}$	2.0	°C/W
Thermal resistance junction-to-ambient	$R_{ hetaJA}$	40	°C/W

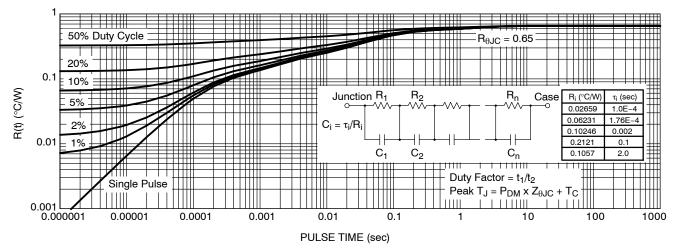
ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified)

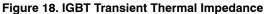
Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit	
STATIC CHARACTERISTIC	•			•			
Collector-emitter breakdown voltage, gate-emitter short-circuited	V_{GE} = 0 V, I _C = 500 μ A	V _{(BR)CES}	1200	_	_	V	
Collector-emitter saturation voltage	V_{GE} = 15 V, I _C = 20 A V _{GE} = 15 V, I _C = 20 A, T _J = 150°C	V _{CEsat}	-	1.80 2.0	2.2 -	V	
Gate-emitter threshold voltage	$V_{GE} = V_{CE}$, $I_C = 250 \ \mu A$	V _{GE(th)}	4.5	5.5	6.5	V	
Collector-emitter cut-off current, gate- emitter short-circuited	V_{GE} = 0 V, V_{CE} = 1200 V V_{GE} = 0 V, V_{CE} = 1200 V, T_{J} = 150°C	I _{CES}		_ _	0.5 2.0	mA	
Gate leakage current, collector-emitter short-circuited	V_{GE} = 20 V, V_{CE} = 0 V	I _{GES}	_	-	100	nA	
DYNAMIC CHARACTERISTIC	•	•					
Input capacitance		C _{ies}	-	4700	-	pF	
Output capacitance	V_{CE} = 20 V, V_{GE} = 0 V, f = 1 MHz	C _{oes}	-	155	-	l	
Reverse transfer capacitance		C _{res}	-	100	-		
Gate charge total		Qg		200		nC	
Gate to emitter charge	V_{CE} = 600 V, I_{C} = 20 A, V_{GE} = 15 V	Q _{ge}		36			
Gate to collector charge		Q _{gc}		98			
SWITCHING CHARACTERISTIC, INDUCT	IVE LOAD						
Turn-off delay time	T _J = 25°C	t _{d(off)}		235		ns	
Fall time	$V_{CC} = 600 \text{ V}, \text{ I}_{C} = 20 \text{ A}$ $R_{g} = 10 \Omega$	t _f		180			
Turn-off switching loss	V _{GE} = 0 V/ 15V	E _{off}		0.7		mJ	
Turn-off delay time	T _J = 125°C	t _{d(off)}		235		ns	
Fall time	$V_{CC} = 600 \text{ V}, \text{ I}_{C} = 20 \text{ A}$ $\text{R}_{g} = 10 \Omega$	t _f		250			
Turn-off switching loss	$V_{GE} = 0 V/15V$	E _{off}		1.60		mJ	
DIODE CHARACTERISTIC							
Forward voltage	V _{GE} = 0 V, I _F = 20 A V _{GE} = 0 V, I _F = 20 A, T _J = 150°C	V _F		1.55 1.65	1.75	V	











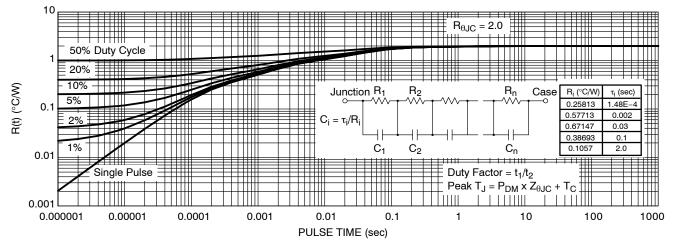


Figure 19. Diode Transient Thermal Impedance

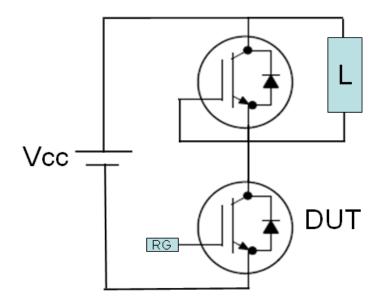
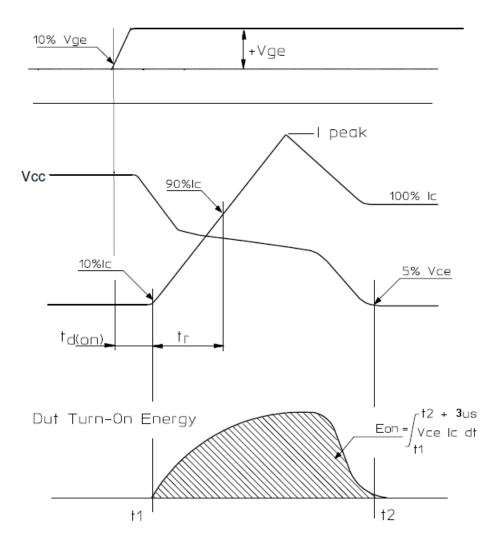
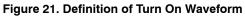


Figure 20. Test Circuit for Switching Characteristics





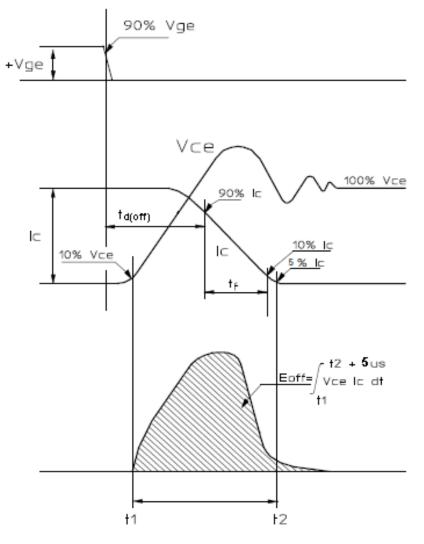
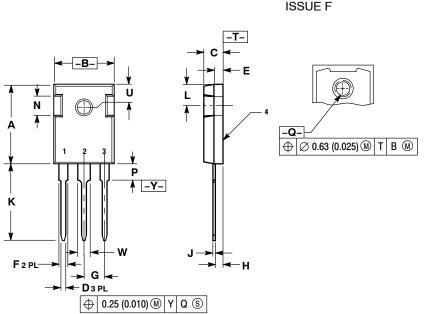


Figure 22. Definition of Turn Off Waveform

PACKAGE DIMENSIONS



TO-247 CASE 340L-02 ISSUE F

TES: DIMENSIONING AND TOLERANCING PER A Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.				
	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	20.32	21.08	0.800	8.30
В	15.75	16.26	0.620	0.640
С	4.70	5.30	0.185	0.209
D	1.00	1.40	0.040	0.055
E	1.90	2.60	0.075	0.102
F	1.65	2.13	0.065	0.084
G	5.45 BSC		0.215 BSC	
Н	1.50	2.49	0.059	0.098
J	0.40	0.80	0.016	0.031
K	19.81	20.83	0.780	0.820
L	5.40	6.20	0.212	0.244
N	4.32	5.49	0.170	0.216
Р		4.50		0.177
Q	3.55	3.65	0.140	0.144
U	6.15	BSC	0.242	2 BSC
W	2.87	3.12	0.113	0.123

STYLE 4: PIN 1. GATE

2. COLLECTOR

3. EMITTER 4. COLLECTOR

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